

Lead-free iC-Haus products / European Directives RoHS and WEEE**TYPE OF CHANGE:**

- Changes in packaging and/or assembly materials

REASON FOR CHANGE:

Switch to lead-free / Optimization of iC-Haus products with regard to:

- Environmental compatibility / European directives RoHS (Restriction of the Use of Certain Hazardous Substances) and WEEE (Waste Electrical and Electronic Equipment)
- Lead-free soldering process required by the customer

The switch to assembly materials optimized for an increased lead-free reflow soldering temperature supports our endeavors to maintain current or achieve better moisture sensitivity levels for lead-free board assembly.

PRODUCTS CONCERNED:

- All iC-Haus products in plastic packages still using SnPb finish for leads and pads for soldering like PLCC, SOIC, SSOP, TSSOP, PDIP, QFN, etc.
- All iC-Haus solder ball products still using SnPb balls, like oBGA.
- All iC-Haus systems still using SnPb solder for assembly, like BMST and iCSY.
- iC-Haus products in BLCC and oLGA packages which do not contain lead or other substances prohibited by EU directive, RoHS may require changes in material in order to be able to withstand the elevated temperature stress generated during lead-free reflow soldering process.

CLASSIFICATION:

- Minor change (information required)

QUALIFICATION:

- Package family-oriented characterization of (moisture-related) sensitivity during lead-free reflow soldering (J-STD 020C) and package reliability tests.

CHARACTERIZATION:

- Soldering conditions adapted to lead-free soldering requirements.
- No other influence on current specifications releases.

PRODUCT/PROCESS CHANGE NOTIFICATION



PCN-05/005

SCHEDULE:

Deliveries

- Up until July 30 2004 only the former version of the product was supplied.
- From August 1 2004 the former versions of the products are gradually replaced by new versions. Deliveries of these new versions are carried out according to the progress made in the qualification process and availability (FIFO).
- From January 1 2006 all products shall be RoHS conform (others on request, only).

MARKING:

iC-Haus products are marked by assembly code which includes a serial assembly lot number. Each delivery note indicates the status of the delivered assembly lot regarding

the substances contained: (either)

- This product **might contain** substances which, for certain new equipment within the EU, are not allowed to be put on market from 1 July 2006 onwards (EU directive 2002/95/EC RoHS from January 27, 2003).
- This product **does not contain** substances prohibited by EU directive RoHS from January 27, 2003.

the resistance to soldering: (either)

- The product is qualified to withstand reflow soldering according to the conditions stipulated by iC-Haus customer info #6, **for eutectic SnPb solder**. The moisture sensitivity level is indicated on the label or moisture barrier bag.
- The product is qualified to withstand reflow soldering according to the conditions stipulated by iC-Haus customer info #7, **for lead-free solder**. The moisture sensitivity level is indicated on the label or moisture barrier bag.
- The product is not subjected to reflow soldering.

For special requirements please contact the iC-Haus sales department.

The status of the individual product can be checked at www.iCHaus.com and will be regularly updated.